

Change in menu Project

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer	Alternate PartNumber	Alternate Manufacturer
PCB	1		Printed Circuit Board		XX###	Any	-	-
C1	1	470pF	CAP, CERM, 470pF, 100V, +/-5%, C0G/NP0, 0805	0805	GRM2165C2A471JA01D	MuRata	-	-
C2, C3, C4	3	100uF	CAP, AL, 100uF, 100V, +/-20%, 0.17 ohm, SMD	SMT Radial J16	EEV-FK2A101M	Panasonic	-	-
C5, C6, C8	3	1uF	CAP, CERM, 1uF, 100V, +/-20%, C Series, 1206	1206	C3216X7R2A105M	TDK	-	-
C7	1	100uF	CAP ALUM 100UF 100V 20% SMD	H0S	EMVH101GDA101MLH0S	United Chemi-Con	-	-
C9	1	0.1uF	CAP, CERM, 0.1uF, 100V, +/-10%, X7R, 0603	0603	GRM188R72A104KA35D	MuRata	-	-
C10, C12, C13	3	100pF	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	0603	GRM1885C1H101JA01D	MuRata	-	-
C11	1	4.7uF	CAP CER 4.7UF 10V 10% X6S 0603	0603 (1608 Metric)	C1608X6S1A475K	TDK Corporation	-	-
C14	1	0.047uF	CAP, CERM, 0.047uF, 25V, +/-10%, X7R, 0603	0603	GRM188R71E473KA01D	MuRata	-	-
C15	1	0.47uF	CAP, CERM, 0.47uF, 100V, +/-10%, X7R, 0805	0805	GRM21BR72A474KA73L	MuRata	-	-
C16	1	0.1uF	CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0603	0603	GRM188R71E104KA01D	MuRata	-	-
C17	1	330pF	CAP, CERM, 330pF, 50V, +/-5%, C0G/NP0, 0603	0603	C1608C0G1H331J	TDK	-	-
C18	1	0.022uF	CAP, CERM, 0.022uF, 50V, +/-10%, X7R, 0603	0603	C1608X7R1H223K	TDK	-	-
D2	1	0.57V	DIODE SCHOTTKY 1A 100V SOD-123FL	SOD-123FL	MBR1H100SFT3G	On Semiconductor	-	-
FID1, FID2, FID3	3		Fiducial mark. There is nothing to buy or mount.	Fiducial	N/A	N/A	-	-
H1, H2, H3, H4	4		Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw	NY PMS 440 0025 PH	B&F Fastener Supply	-	-
H5, H6, H7, H8	4		Standoff, Hex, 0.5"L #4-40 Nylon	Standoff	1902C	Keystone	-	-
L1	1	4uH	Inductor, Shielded E Core, Ferrite, 4uH, 25A, 0.00194 ohm, SMD	SER2014	SER2014-402MLB	Coilcraft	-	-
LBL1	1		Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W	THT-14-423-10	Brady	-	-
Q1, Q2, Q3	3	80V	MOSFET, N-CH, 80V, 55A, PG-TDSON-8	PG-TDSON-8	BSC123N08NS3 G	Infineon Technologies	-	-
R1	1	7.5	RESISTOR 7.5 OHM 3/4W 5% 2010	2010	ERJ-12ZYJ7R5U	Panasonic	-	-
R2	1	0.004	RES, 0.004 ohm, 1%, 1W, 2512	2512	ERJ-M1WSF4M0U	Panasonic	-	-
R3, R4, R5, R6, R8, R12, R21	7	0	RES, 0 ohm, 5%, 0.1W, 0603	0603	ERJ-3GEY0R00V	Panasonic	-	-
R10	1	49.9k	RES, 49.9k ohm, 1%, 0.1W, 0603	0603	CRCW060349K9FKEA	Vishay-Dale	-	-
R11	1	3.3	RES, 3.3 ohm, 5%, 0.1W, 0603	0603	CRCW06033R30JNEA	Vishay-Dale	-	-
R13	1	8.66k	RES, 8.66k ohm, 1%, 0.1W, 0603	0603	CRCW06038K66FKEA	Vishay-Dale	-	-
R14	1	10.0k	RES, 10.0k ohm, 1%, 0.1W, 0603	0603	CRCW060310K0FKEA	Vishay-Dale	-	-
R16	1	40.2k	RES, 40.2k ohm, 1%, 0.1W, 0603	0603	CRCW060340K2FKEA	Vishay-Dale	-	-
R17	1	15.0k	RES, 15.0k ohm, 1%, 0.1W, 0603	0603	CRCW060315K0FKEA	Vishay-Dale	-	-
R18	1	2.15k	RES, 2.15k ohm, 1%, 0.1W, 0603	0603	CRCW06032K15FKEA	Vishay-Dale	-	-
R19	1	84.5k	RES, 84.5k ohm, 1%, 0.1W, 0603	0603	CRCW060384K5FKEA	Vishay-Dale	-	-
R20	1	3.48	RES, 3.48 ohm, 1%, 0.1W, 0603	0603	CRCW06033R48FKEA	Vishay-Dale	Equivalent	Any
TP1, TP2, TP3, TP4	4		Standard Banana Jack, Uninsulated, 8.9mm	Keystone575-8	575-8	Keystone	Equivalent	Any
TP5, TP7	2	Red	Test Point, TH, Multipurpose, Red	Keystone5010	5010	Keystone	Equivalent	Any
TP6, TP8, TP10	3	Black	Test Point, TH, Multipurpose, Black	Keystone5011	5011	Keystone	Equivalent, -, -	Any, -, -
TP9, TP11	2	White	Test Point, TH, Miniature, White	Keystone5002	5002	Keystone	-	-
TP12	1	White	Test Point, TH, Multipurpose, White	Keystone5012	5012	Keystone	Equivalent	Any
U1	1			eg: 0603, used in PnP report	LM5122MH	TI	-	-
D1	0	0.77V	Diode, Schottky, 100V, 1A, PowerDI123	PowerDI123	DFLS1100-7	Diodes Inc.	-	-
R7	0	158k	RES, 158k ohm, 1%, 0.1W, 0603	0603	CRCW0603158KFKEA	Vishay-Dale	-	-
R9	0	DNP	RES, 3.3 ohm, 5%, 0.1W, 0603	0603	CRCW06033R30JNEA	Vishay-Dale	-	-
R15	0	DNP	RES, 0 ohm, 5%, 0.1W, 0603	0603	ERJ-3GEY0R00V	Panasonic	-	-

Notes:
Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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